

A

B

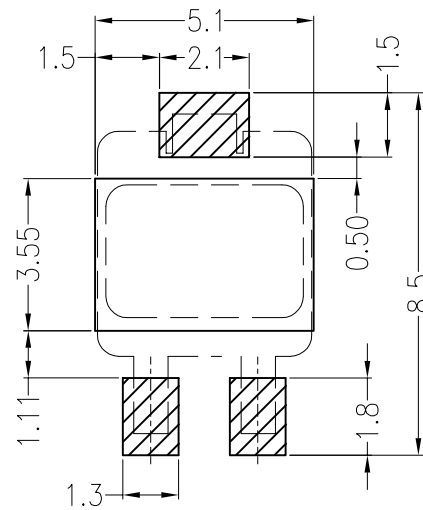
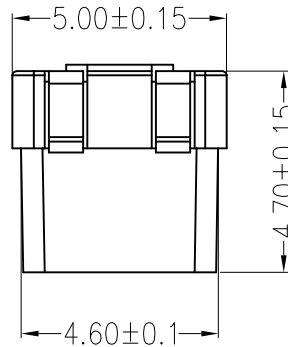
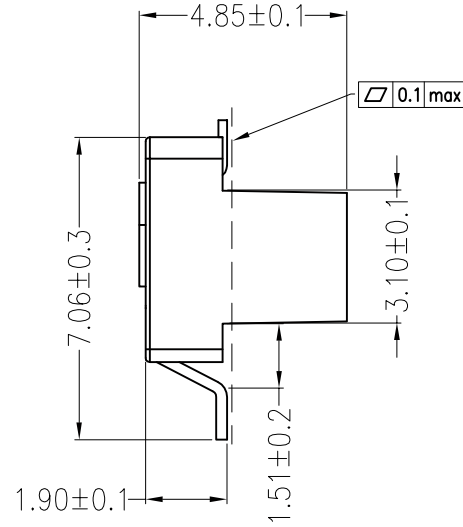
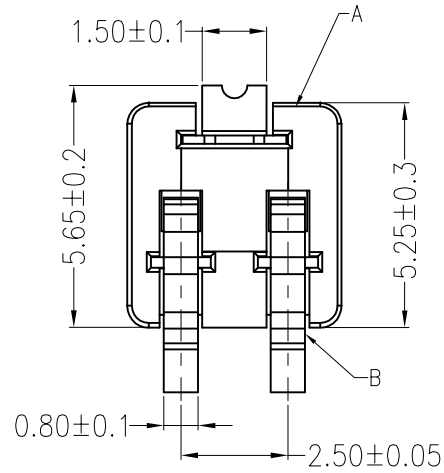
C

D

E

F

REV	DESCRIPTION	DESIGN	DATE
A0	Release	吴丹平	2016.04.30



Board Layout

主要技术参数 Main Specifications

线 数 (Poles): 02 to 06

接触电阻 (Contact resistance): $\leq 20\text{m}\Omega$

绝缘电阻 (Insulation resistance): $\geq 1000\text{M}\Omega$

额定电压 (Rated voltage): 125V AC DC

额定电流 (Rated current): 1.0A AC DC

耐 电压 (Withstand Voltage): 1000V AC/minute

温度范围 (Temperature Range): $-40^{\circ}\text{C} \sim +130^{\circ}\text{C}$

C	Solder Tab	1 PCS	PhosphorBronze	MATTE Sn-plated
B	CONTACT	2 PCS	PhosphorBronze	MATTE Sn-plated
A	PEDESTAL	1 PCS	LCP	UL 94V-0, COLOR:BEIGE
ITEM	COMPONENT	Q'TY	MATERIAL	FINISH
LEDsconn				TITLE: - 2.5mmPITCH 180°WAFER SMT TYPE
X.±0.5	X.±5'	USE: CUSTOMER		PART NO.:
.X±0.3	.X±2'	APPD: 邵敬和		DWG NO.:
.XX±0.25	.XX±1'	CHKD: 田峰		
--	--	DR: 吴丹平		SCALE 1 : 1
UNITS: mm				SHEET 1 / 1

1

2

3

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A

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